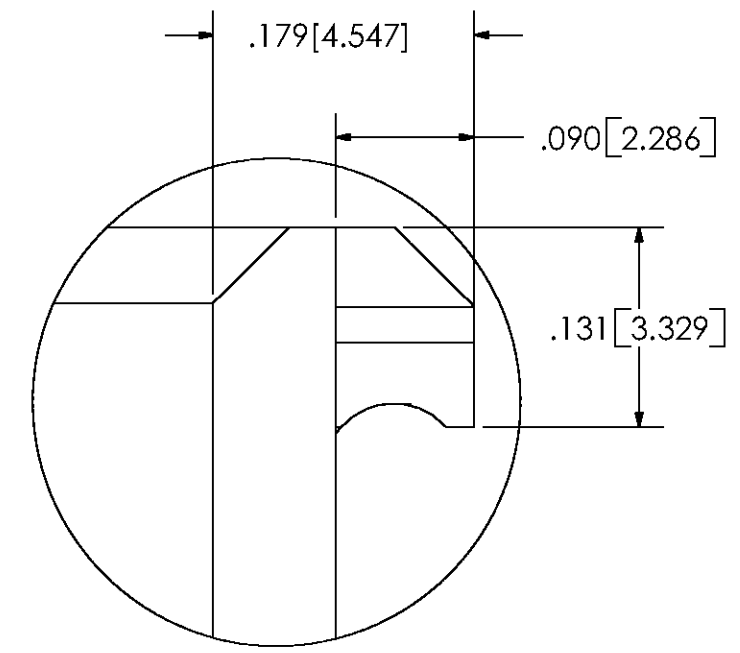
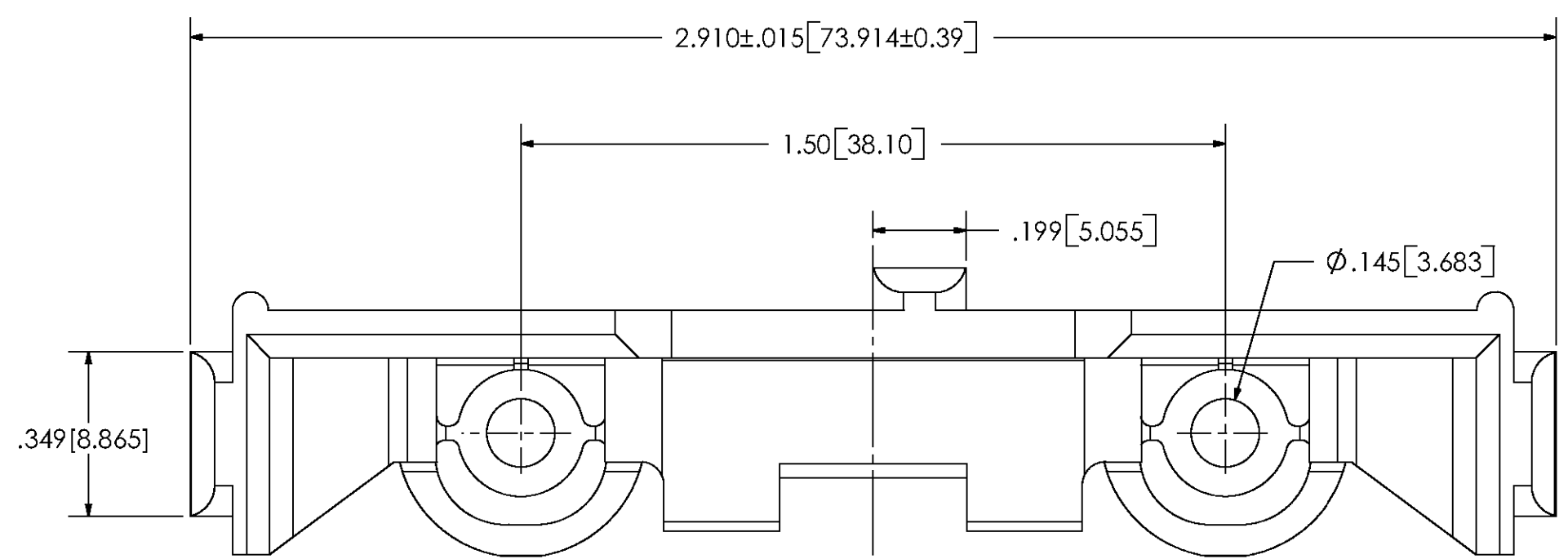
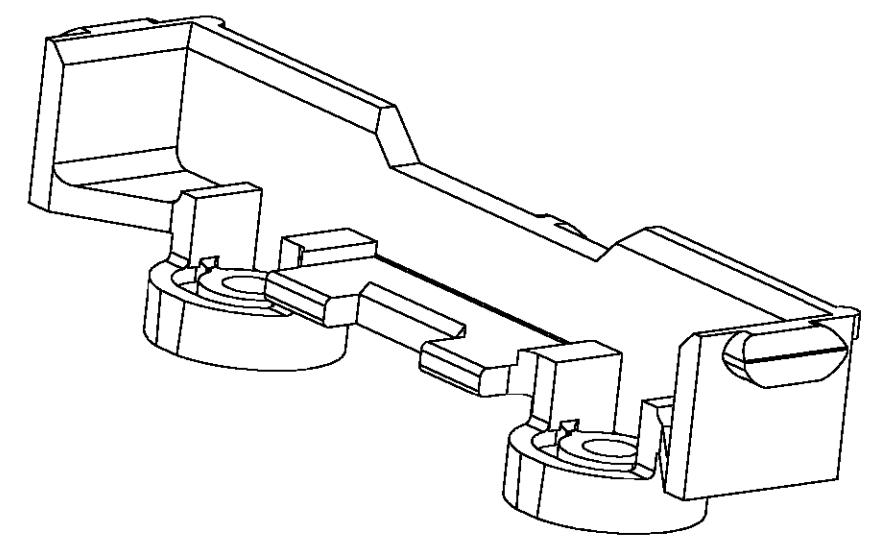


8 7 6 5 4 3 2 1

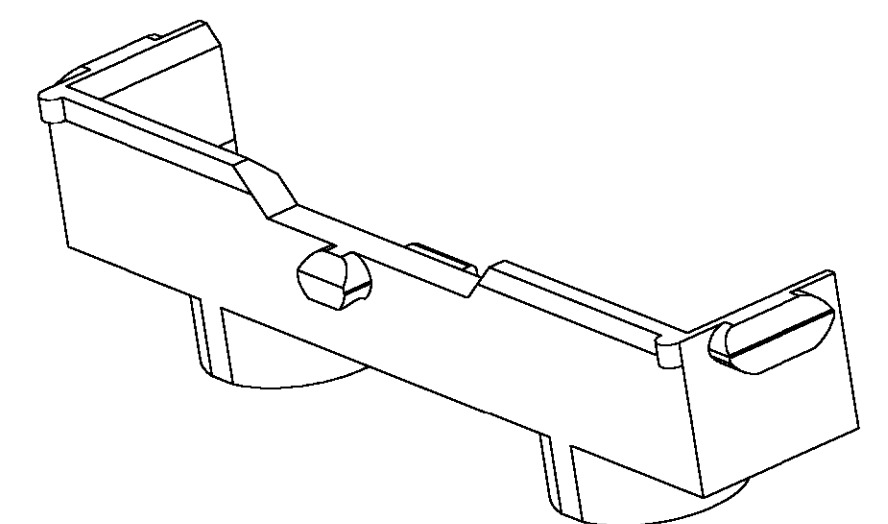
F
E
D
C
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A



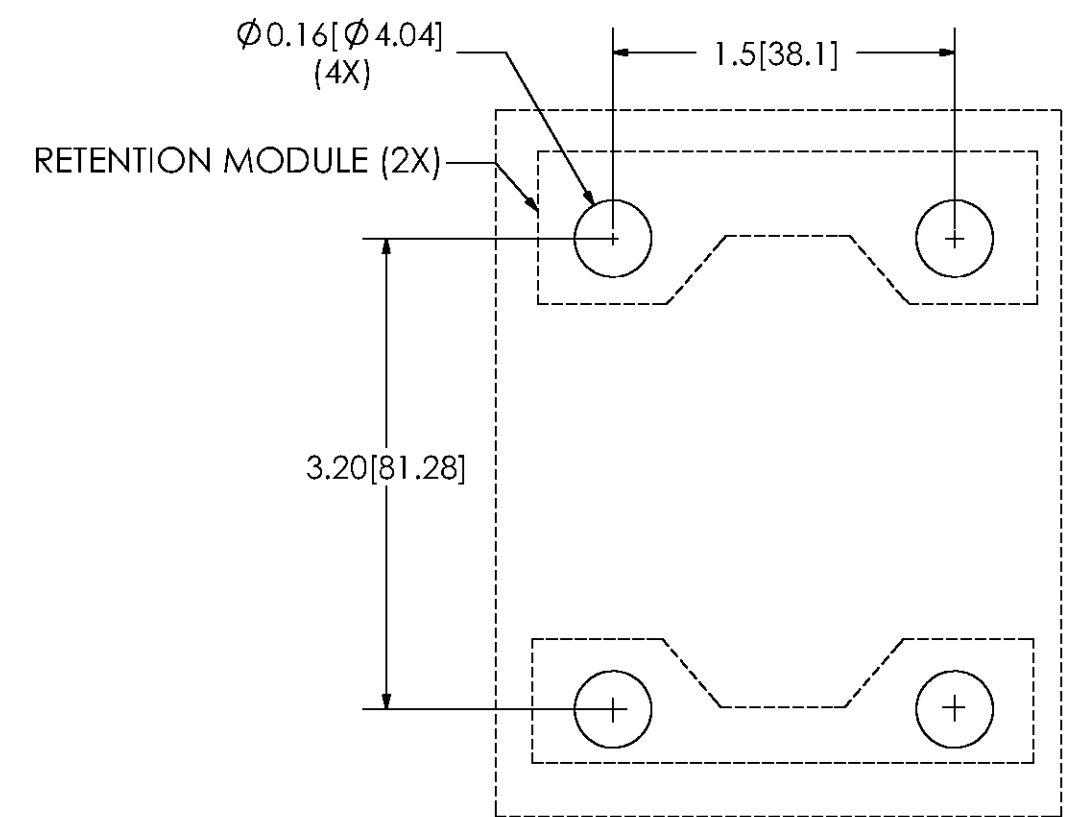
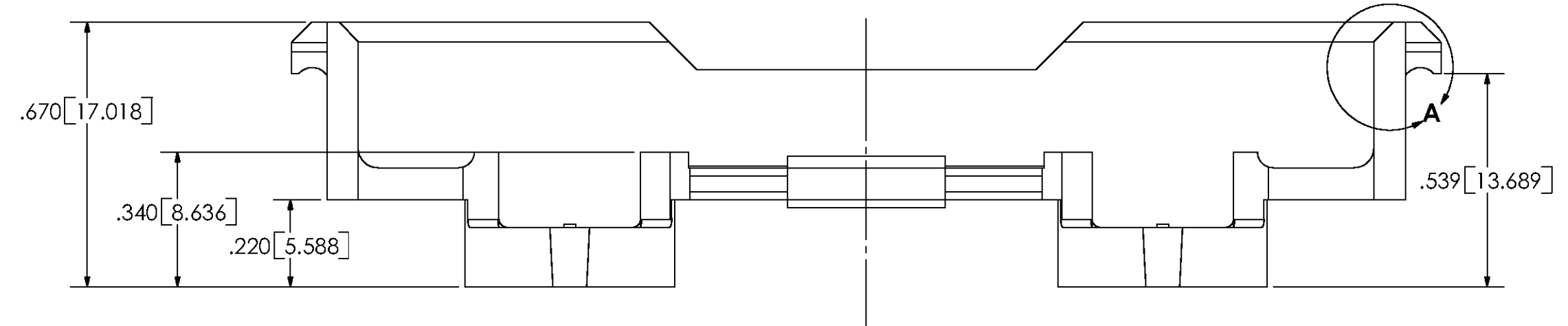
**DETAIL A
SCALE= 8X**



SCALE= 2X



SCALE= 2X



**PCB LAYOUT
REFERENCE DIMENSIONS FROM INTEL®
DESIGN GUIDE**

NOTES:

- 1.) 2 RETENTION MODULES REQUIRED PER HEAT SINK.
- 2.) RETENTION MODULE USED WITH XEON PROCESSOR HEAT SINKS.
- 3.) QUICK RELEASE CLIP AVAILABLE FOR FLIP CHIP P/N: 9-1542007-7.

CUSTOMER DRAWING

SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE

REV.	REVISION INFO
A	RELEASE OS60-0045-03 E.TAO 04/09/03 APP'D: S.G 04/09/03
B	RELEASE OS60-0127-03 E.TAO 10/02/03 APP'D: A.M 10/02/03
C	RELEASE OS60-0061-03 E.TAO 03/11/04 APP'D: B.P 03/15/04
D	REVISED OS60-0214-04 E.TAO 8/23/04 APP'D: S.D 9/2/04

DO NOT SCALE	tyco Electronics Attleboro Falls Massachusetts 02763																					
	UNLESS OTHERWISE SPECIFIED TOLERANCES ARE:																					
	<table border="0"> <tr> <td>DRAWN BY:</td> <td>E.TAO</td> <td>DATE:</td> <td>03/07/03</td> </tr> <tr> <td>ENGINEER:</td> <td>S.G</td> <td>DATE:</td> <td>03/07/03</td> </tr> <tr> <td>FILENAME:</td> <td>9-1542007-5</td> <td>PROJECT:</td> <td>-</td> </tr> <tr> <td>SYSTEM:</td> <td colspan="2">SolidWorks</td> <td></td> </tr> </table>	DRAWN BY:	E.TAO	DATE:	03/07/03	ENGINEER:	S.G	DATE:	03/07/03	FILENAME:	9-1542007-5	PROJECT:	-	SYSTEM:	SolidWorks			<table border="0"> <tr> <td>MATERIAL:</td> <td>LEXAN (BLACK) FLAMMABILITY: UL 94V-0.</td> </tr> <tr> <td>FINISH:</td> <td>-</td> </tr> </table>	MATERIAL:	LEXAN (BLACK) FLAMMABILITY: UL 94V-0.	FINISH:	-
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TITLE:	RETENTION MODULE FOR XEON PROCESSOR																					
TYCO PART NO:	9-1542007-5																					
DWG. NO.:	C-9-1542007-5																					

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REV D	

8 7 6 5 4 3 2 1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)